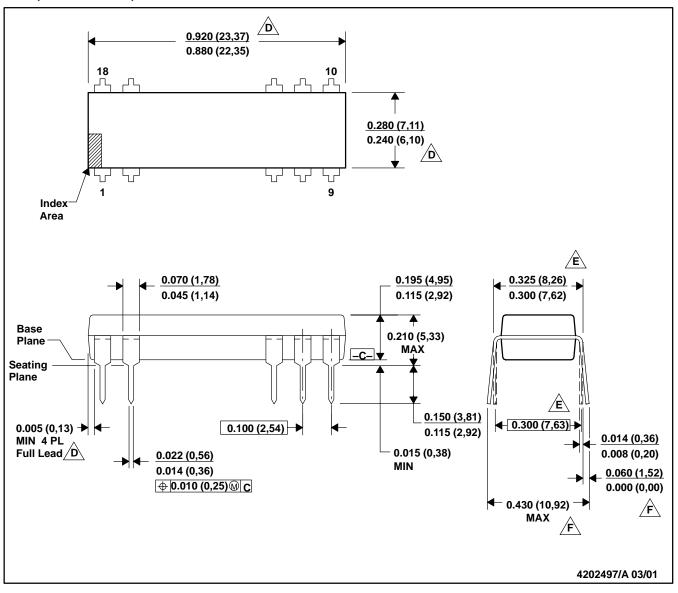
MECHANICAL DATA

MPDI055 - APRIL 2001



PLASTIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001-AC with the exception harphi of lead count.
 - Δ Dimensions do not include mold flash or protrusions.
 - Mold flash or protrusions shall not exceed 0.010 (0,25). \triangle Dimensions measured with the leads constrained to be perpendicular to Datum C.
 - <u>F.</u> Dimensions are measured at the lead tips with the leads unconstrained.
 - G. A visual index feature must be located within the cross-hatched area.



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